Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims

in the applications.

Listing of Claims:

Claim 1 (currently amended)

A measuring system of a gas-stream environment, said measuring

system comprises comprising:

a stage, wherein-said stage is located locating on a transport apparatus

and used to place a wafer placing on said stage;

a datum platen, wherein-said datum platen is located locating on said

transport apparatus and on a side of said stage to be used to place a datum

slice;

a lens, wherein said lens is located locating above said stage to measure

the thickness of said wafer and said datum slice;

a gas supplier, wherein said gas supplier is used to supplysupplying a

gas;

side of said datum platen;

a second gas nozzle, wherein-said second gas nozzle is located locating

on a side of said stage;

a first tube, wherein said first tube is connected connecting with said first

gas nozzle and said gas supplier;

a second tube, wherein-said second tube is connected connecting with

said second gas nozzle and with said gas suppler, wherein said gas supplier

supplied said gas passing through said first tube and said second tube, and

exhausted from said first gas nozzle and said second gas nozzle to form a

gas stream;

a transport slot, wherein said transport slot is an opening to exhaust said

gas and is used to collecting said gas in said gas stream, and used using to

beas a channel to exhaust said gas stream; and

a gas-extracting apparatus, wherein—said gas-extracting apparatus

connects connecting with said transport slot by using a third tube.

Claim 2 (currently amended)

The measuring system according to claim 1, wherein further comprising a

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first flow rate regulating valve fixing on said first gas nozzle.

Claim 3 (currently amended)

The measuring system according to claim 1, wherein further comprising a

second flow rate regulating valve is fixed fixing on said second gas nozzle.

Claim 4 (currently amended)

The measuring system according to claim 1, wherein said gas-extracting

apparatus comprises a gas-extracting motor.

Claim 5 (currently amended)

The measuring system according to claim 1, wherein said gas-extracting

apparatus comprises a venture structure.

Claim 6 (currently amended)

The measuring system according to claim 1, wherein said gas is an inert

gas.

Claim 7 (currently amended)

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The measuring system according to claim 1, wherein said gas is nitrogen.

Claim 8 (cancelled)

Claim 9 (currently amended)

A measuring system of a gas-stream environment, said measuring

system comprises comprising:

a stage, wherein-said stage is locatedlocating on a transport apparatus

and is used to place a wafer placing on said stage;

a datum platen, wherein-said datum platen is located locating on said

transport apparatus and on a side of said stage to be used to place a datum

slice;

a lens, wherein said lens is located ocating above said stage to measure

the thickness of said wafer and said datum slice;

a gas supplier, wherein said gas supplier is used to supplysupplying a

gas;

a first gas nozzle, wherein said first gas nozzle is located locating on a

side of said datum platen;

a second gas nozzle, wherein said second gas nozzle is located locating

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on a side of said stage;

a first tube, wherein said first tube is connected connecting with said first

gas nozzle and with said supplier;;

a second tube, wherein said second tube is connected connecting with

said second gas nozzle and with said gas supplier, wherein said gas supplier

supplied said gas assign through said first tube and said second tube, and

exhausted from said first gas nozzle and said second gas nozzle to form a

gas stream;

a transport slot, wherein said transport slot is an openingextracting said

gas; and

a gas-extracting apparatus, wherein—said gas-extracting apparatus

connects connecting with said transport slot by using a third tube.

Claim 10 (currently amended)

The measuring system according to claim 9, wherein said first tube

comprises a first flow rate regulating valve.

Claim 11 (currently amended)

The measuring system according to claim 9, wherein said second tube

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comprises a second flow rate regulating valve.

Claim 12 (currently amended)

The measuring system according to claim 9, wherein said gas-extracting

apparatus comprises a gas-extracting motor.

Claim 13 (currently amended)

The measuring system according to claim 9, wherein said gas-extracting

apparatus comprises a venture structure.

Claim 14(currently amended)

The measuring system according to claim 9, wherein said gas is an inert

gas.

Claim 15 (currently amended)

The measuring system according to claim 9, wherein said gas is a

nitrogen.

Claim 16 (cancelled)

Claim 17 (currently amended)

A measuring system of a gas-stream environment, said measuring

system comprises comprising:

a stage, wherein said stage is located locating on a transport apparatus

and is used to place a wafer placing on said stage;

a datum platen, wherein said datum platen is located locating on said

transport apparatus and on a side of said stage to be used to place a datum

slice;

a lens, wherein-said lens is located locating above said stage to measure

the thickness of said wafer and said datum slice;

a gas supplier, wherein said gas supplier is used to supply supplying a

gas in a gas stream;

a first gas nozzle, wherein-said first gas nozzle is locatedlocating on a

side of said datum platen and on said transport apparatus to exhaust said gas

in said gas stream;

a second gas nozzle, wherein-said second gas nozzle is located locating

on a side of said stage and on said transport apparatus to exhaust said gas in

said gas stream;

a first tube, wherein-said first tube comprises having a first flow rate

regulating valve, and is connected connecting with said first gas nozzle and

with said gas supplier;

a second tube, wherein-said second tube comprises-having a second

flow rate regulating valve and is connected connecting with said second gas

nozzle and with said gas supplier;

a transport slot, wherein-said transport slot is an opening to exhaust said

gas; and

a gas-extracting apparatus, wherein said gas-extracting apparatus

connects connecting with said transport slot by using a third tube and is used

to produce producing an attraction to remove said gas.

Claim 18 (currently amended)

The measuring system according to claim 17, wherein said gas-extracting

apparatus comprises a venture structure.

Claim 19 (currently amended)

The measuring system according to claim 17, wherein said gas is an inert

gas.

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Claim 20 (currently amended)

The measuring system according to claim 17, wherein said gas is

nitrogen.

Claim 21 (currently amended)

The measuring system according to claim 1, wherein said first gas nozzle

used to exhaust a gas in a gas stream.

Claim 22 (currently amended)

The measuring system according to claim 1, wherein said transport slot

used collect said gas in said gas stream.

Claim 23 (currently amended)

The measuring system according to claim 1, wherein said transport slot

used to be a channel to exhaust said gas in said gas stream.

Claim 24 (New)

The measuring system according to claim 1, wherein said lens to

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measure said thickness of said wafer comprises:

placing said wafer on said stage by using a robot;

moving said stage to the place under said lens by using said transport

device;

irradiating a light from said lens to a surface of said wafer and the data,

wherein said data returned from said light and showed on a monitor; and

analyzing said data to obtain said thickness of said wafer.

Claim 25 (New)

The measuring system according to claim 9, wherein said lens to

measure said thickness of said wafer comprises:

placing said wafer on said stage by using a robot;

moving said stage to the place under said lens by using said transport

device;

irradiating a light from said lens to a surface of said wafer and the data,

wherein said data returned from said light and showed on a monitor; and

analyzing said data to obtain said thickness of said wafer.

Claim 26 (New)

The measuring system according to claim 17, wherein said lens to

measure said thickness of said wafer comprises:

placing said wafer on said stage by using a robot;

moving said stage to the place under said lens by using said transport

device;

irradiating a light from said lens to a surface of said wafer and the data,

wherein said data returned from said light and showed on a monitor; and

analyzing said data to obtain said thickness of said wafer.